



Product Change Notification: DSNO-15CEZA864

Date:

17-Jun-2026

Product Category:

Gate Drivers and Motor Drivers, LIN Transceiver With Vreg

Notification Subject:

CCB 7829.001 Final Notice: Qualification of MMT as an additional assembly site for selected MCP1403T, MCP1404T, MCP1405T, MCP1406T, MCP1407T, MCP140x, MCP14E10T, MCP14E11T, MCP14E1x, MCP14E3T, MCP14E4T, MCP14E5T, MCP14E6T, MCP14E7T, MCP14E8T, MCP14E9T, MCP14Ex, MCP201T, MCP2021, MCP2021T, TC442xx and TC445x device families available in 8L DFN-S (6x5x0.9mm) package.

Affected CPNs:

[DSNO-15CEZA864_Affected_CPN_06172026.pdf](#)

[DSNO-15CEZA864_Affected_CPN_06172026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MMT as an additional assembly site for selected MCP1403T, MCP1404T, MCP1405T, MCP1406T, MCP1407T, MCP140x, MCP14E10T, MCP14E11T, MCP14E1x, MCP14E3T, MCP14E4T, MCP14E5T, MCP14E6T, MCP14E7T, MCP14E8T, MCP14E9T, MCP14Ex, MCP201T, MCP2021, MCP2021T, TC442xx and TC445x device families available in 8L DFN-S (6x5x0.9mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)

Assembly Site	Amkor Technology Philippines (P3/P4), INC. (ATP7)	UTAC Thai Limited (UTL-1 (NSEB))	Amkor Technology Philippines (P3/P4), INC. (ATP7)	UTAC Thai Limited (UTL-1 (NSEB))	Microchip Technology Thailand (Branch) (MMT)	Yes
Wire Material	Au	Au	Au	Au	Au	No
Die Attach Material	QMI536 (PFAS-affected) AMK-06 (PFAS-free)	8006NS (PFAS-free) 8600 (PFAS-affected)	QMI536 (PFAS-affected) AMK-06 (PFAS-free)	8006NS (PFAS-free) 8600 (PFAS-affected)	8006NS (PFAS-free) QMI519 (PFAS-free)	Yes
Molding Compound Material	G700	G700LTD G770HC D	G700	G700LTD G770HC D	G700LTD	Yes
Lead-Frame Material	C194	C194 EFTEC-64T	C194	C194 EFTEC-64T	C194	Yes
DAP Surface Prep	Ag	Ag Ring	Ag	Ag Ring	Bare Cu	Yes
Lead-Frame Lead-Lock	Yes (Half-etch)	Yes (Dimple)	Yes (Half-etch)	Yes (Dimple)	Yes (Half-etch)	Yes
Lead-Frame Design	See Pre and Post Change Summary attachment for comparison.					

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery and manufacturability by qualifying MMT as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 03 August 2026 (date code: 2632)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	June 2026					>	August 2026				
Work Week	23	24	25	26	27		32	33	34	35	36
Qual Report Availability			x								
Final PCN Issue Date			x								
Estimated Implementation Date							x				

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: June 17, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_DSNO-15CEZA864_Pre_and_Post_Change Summary.pdf](#)

[PFAS Elimination and Die Attach Explanation.pdf](#)

[PCN_DSNO-15CEZA864_Qualification Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.



Affected Catalog Part Numbers (CPN):

TC4423EMF713

TC4423VMF

TC4423VMF713

TC4424AVMF

TC4424AVMF713

TC4424EMF

TC4424EMF713

TC4424VMF

TC4424VMF713

TC4425AVMF

TC4425AVMF713

TC4425EMF

TC4425EMF713

TC4429VMF713

TC4451VMF

TC4451VMF713

TC4452VMF

TC4452VMF713

MCP14E9T-E/MF

MCP201T-E/MF

MCP2021-330E/MF

MCP2021-500E/MF

MCP2021T-330E/MF

MCP2021T-500E/MF

TC4420EMF

TC4420EMF713

TC4420VMF

TC4420VMF713

TC4421AVMF

TC4421AVMF713

TC4421EMF

TC4421EMF713

DSNO-15CEZA864 - CCB 7829.001 Final Notice: Qualification of MMT as an additional assembly site for selected MCP1403T, MCP1404T, MCP1405T, MCP1406T, MCP1407T, MCP140x, MCP14E10T, MCP14E11T, MCP14E1x, MCP14E3T, MCP14E4T, MCP14E5T, MCP14E6T, MCP14E7T, MCP14E8T, MCP14E9T, MCP14Ex, MCP201T, MCP2021, MCP2021T, TC442xx and TC445x device families available in 8L DFN-

TC4421VMF

TC4421VMF713

TC4422AVMF

TC4422AVMF713

TC4422EMF

TC4422EMF713

TC4422VMF

TC4422VMF713

TC4423AVMF

TC4423AVMF713

TC4423EMF

TC4428AEMF713

TC4428AVMF

TC4428AVMF713

TC4428EMF

TC4428EMF713

TC4428VMF

TC4428VMF713

TC4429EMF

TC4429EMF713

TC4429VMF

MCP1403-E/MF

MCP1403T-E/MF

MCP1404-E/MF

MCP1404T-E/MF

MCP1405-E/MF

MCP1405T-E/MF

MCP1406-E/MF

MCP1406T-E/MF

MCP1407-E/MF

MCP1407T-E/MF

MCP14E10-E/MF

MCP14E10T-E/MF

MCP14E11-E/MF

MCP14E11T-E/MF

MCP14E3-E/MF

MCP14E3T-E/MF

MCP14E4-E/MF

MCP14E4T-E/MF

MCP14E5-E/MF

MCP14E5T-E/MF

MCP14E6-E/MF

MCP14E6T-E/MF

MCP14E7-E/MF

MCP14E7T-E/MF

MCP14E8-E/MF

MCP14E8T-E/MF

MCP14E9-E/MF

TC4425VMF

TC4425VMF713

TC4426AEMF

TC4426AEMF713

TC4426AVMF

TC4426AVMF713

TC4426EMF

TC4426EMF713

TC4426VMF

TC4426VMF713

TC4427AEMF

TC4427AEMF713

TC4427AVMF

TC4427AVMF713

TC4427EMF

TC4427EMF713

TC4427VMF

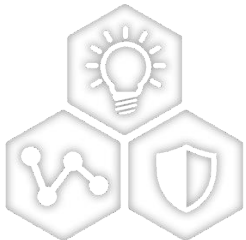
TC4427VMF713

TC4428AEMF

CCB 7829.001
Pre and Post Change Summary
PCN #: DSNO-15CEZA864



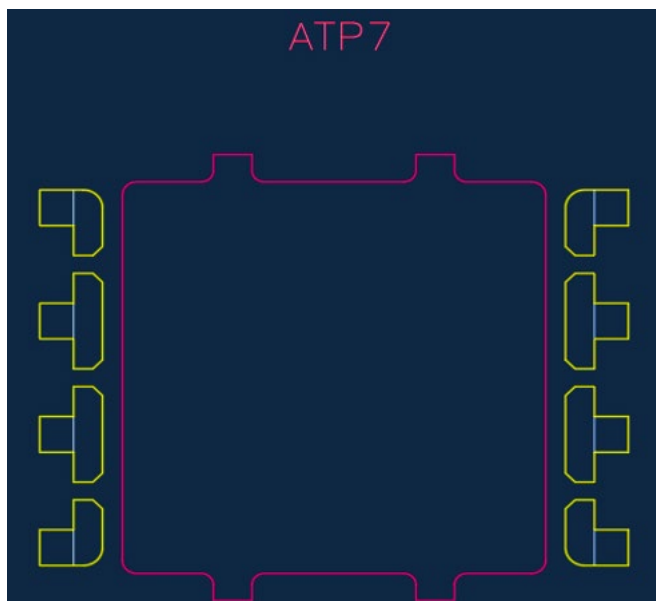
A Leading Provider of Smart, Connected and Secure Embedded Control Solutions



SMART | CONNECTED | SECURE

Lead Frame Comparison

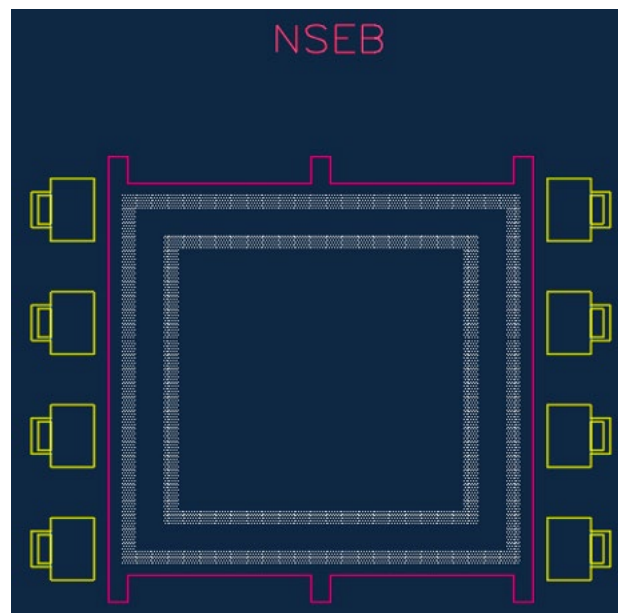
ATP7



Note: Not to scale

Lead Frame Material	C194
DAP Surface Prep	Ag
Lead Frame Lead-Lock	Half-etch

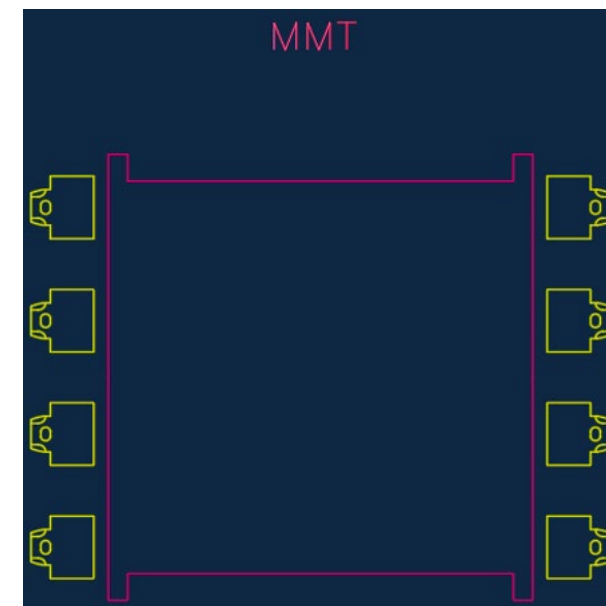
NSEB



Note: Not to scale

Lead Frame Material	C194 / EFTEC-64T
DAP Surface Prep	Ag Ring
Lead Frame Lead-Lock	Dimple

MMT



Note: Not to scale

Lead Frame Material	C194
DAP Surface Prep	Bare Cu
Lead Frame Lead-Lock	Half-etch



QUALIFICATION REPORT SUMMARY
RELIABILITY LABORATORY

PCN #: DSNO-15CEZA864

Date:
June 15, 2026

Qualification of MMT as an additional assembly site for MIC5060YML-TR catalog part number (CPN) available in 8L VDFN (3x3x0.9mm) package. Qualification of MMT as an additional assembly site for selected MCP1403T, MCP1404T, MCP1405T, MCP1406T, MCP1407T, MCP140x, MCP14E10T, MCP14E11T, MCP14E1x, MCP14E3T, MCP14E4T, MCP14E5T, MCP14E6T, MCP14E7T, MCP14E8T, MCP14E9T, MCP14Ex, MCP201T, MCP2021, MCP2021T, TC442xx and TC445x device families available in 8L DFN-S (6x5x0.9mm) package. This is a qualification by similarity (QBS).



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PACKAGE QUALIFICATION REPORT

Purpose	Qualification of MMT as an additional assembly site for MIC5060YML-TR catalog part number (CPN) available in 8L VDFN (3x3x0.9mm) package. Qualification of MMT as an additional assembly site for selected MCP1403T, MCP1404T, MCP1405T, MCP1406T, MCP1407T, MCP140x, MCP14E10T, MCP14E11T, MCP14E1x, MCP14E3T, MCP14E4T, MCP14E5T, MCP14E6T, MCP14E7T, MCP14E8T, MCP14E9T, MCP14Ex, MCP201T, MCP2021, MCP2021T, TC442xx and TC445x device families available in 8L DFN-S (6x5x0.9mm) package. This is a qualification by similarity (QBS).
CN	E000140867
QUAL ID	R2201344 Rev. A.
MP CODE	20838TJMAA01
Part No.	MIC5060YML-TR
Bonding No.	BD-000765 Rev.02
CCB No.:	5229 (Qual Date: September 28, 2023) and 7829.001
<u>Package</u>	
Type	8L VDFN
Package size	3 x 3 x 0.9 mm
<u>Lead Frame</u>	
Paddle size	71 x 102 mils
Material	A194
Surface	NiPdAu-PPF
Process	Etched
Lead Lock	Yes
Part Number	10100862
Treatment	ME2
<u>Material</u>	
Epoxy	8006NS
Wire	Au wire
Mold Compound	G700LTD
Plating Composition	NiPdAu



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PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-233102091.000	TMPE223067675.100	2244QUY
MMT-233201719.000	TMPE223067675.100	2245V56
MMT-233201650.000	TMPE223067675.100	2245USA

Result

☒

Pass

☐

Fail

☐

8L VDFN (3x3x0.9 mm) assembled by MMT pass reliability test per QCI-39000.
This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C
reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Precondition Prior Perform Reliability Tests (At MSL Level 1)	Electrical Test: +25°C System: TMT	JESD22- A113	693(0)	0/693		Good Devices
	Bake 150°C, 24 hrs. System: CHINEE	JIP/ IPC/JEDEC J-STD-020E		693		
	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243			693		
	Electrical Test: +25°C System: TMT		693(0)	0/693	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: -65°C to +150°C, 500 Cycles System: TABAI ESPEC TSA-70H	JESD22-A104		0/231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: TMT		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (>4.00 grams)		15(0)	0/15	Pass	
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118		0/231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: TMT		231(0)	0/231	Pass	77 units / lot
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: VDD 5.0 Volts System: HAST 6000X	JESD22-A110		0/231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: TMT		231(0)	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	Stress Condition: Bake 175°C, 504 hrs. System: SHEL LAB Electrical Test: +25°C System: TMT	JESD22-A103	45(0)	0/45 0/45	Pass	45 units
Solderability Temp 215°C	Steam Aging: Temp 93°C, 1Hrs System: SAS-3000 Solder Dipping: Solder Temp. 215°C Solder material: SnPb Sn63, Pb37 System: ERS A RA 2200D Visual Inspection: External Visual Inspection	J-STD-002	22(0)	0/22 0/22 0/22	Pass	
Solderability Temp 245°C	Steam Aging: Temp 93°C, 1Hrs System: SAS-3000 Solder Dipping: Solder Temp. 245°C Solder material: Pb Free Sn 95.5Ag3.9 Cu0.6 System: ERS A RA 2200D Visual Inspection: External Visual Inspection	J-STD-002	22(0)	0/22 0/22 0/22	Pass	
Wire sweep	Wire sweep Inspection 15 Wires / lot	-	45(0) Wires	0/45	Pass	
Physical Dimensions	Physical Dimension, 10 units / 1 lot	JESD22-B100/B108	30(0) Units	0/30	Pass	
Bond Strength Data Assembly	Wire Pull (>4.00 grams) Bond Shear (>18.00 grams)	Mil. Std. 883-2011 CDF-AEC-Q100-001	30(0) Wires 30(0) bonds	0/30 0/30	Pass Pass	



QUALIFICATION REPORT SUMMARY

PCN#: DSNO-15CEZA864

**Date:
June 15, 2026**

Qualification of MMT as an additional assembly site for selected 25AA1024, 25AA512, 25AA640A, 25LC1024, 25LC256, 25LC512, PIC12F635 and PIC12F683 device families available in 8L DFN-S (6x5x0.9mm) package. This is a Q006 Grade 1 qualification.

Qualification of MMT as an additional assembly site for selected MCP1403T, MCP1404T, MCP1405T, MCP1406T, MCP1407T, MCP140x, MCP14E10T, MCP14E11T, MCP14E1x, MCP14E3T, MCP14E4T, MCP14E5T, MCP14E6T, MCP14E7T, MCP14E8T, MCP14E9T, MCP14Ex, MCP201T, MCP2021, MCP2021T, TC442xx and TC445x device families available in 8L DFN-S (6x5x0.9mm) package. This is a qualification by similarity (QBS).



MICROCHIP PACKAGE QUALIFICATION REPORT

Purpose	Qualification of MMT as an additional assembly site for selected 25AA1024, 25AA512, 25AA640A, 25LC1024, 25LC256, 25LC512, PIC12F635 and PIC12F683 device families available in 8L DFN-S (6x5x0.9mm) package. This is a Q006 Grade 1 qualification. Qualification of MMT as an additional assembly site for selected MCP1403T, MCP1404T, MCP1405T, MCP1406T, MCP1407T, MCP140x, MCP14E10T, MCP14E11T, MCP14E1x, MCP14E3T, MCP14E4T, MCP14E5T, MCP14E6T, MCP14E7T, MCP14E8T, MCP14E9T, MCP14Ex, MCP201T, MCP2021, MCP2021T, TC442xx and TC445x device families available in 8L DFN-S (6x5x0.9mm) package. This is a qualification by similarity (QBS).
QUAL ID	R2501401 Rev. B
Bonding No.	BD-003678 Rev.01
MP CODE	DECR24A6XA00
Part No.	25LC1024-E/MF
CCB No.	7829 (Qual Date: September 11, 2025) and 7829.001
<u>Lead Frame</u>	
Paddle size	173x173
Material	C194
Surface	Bare Cu
Process	Etched LF
Lead lock	Dimple
Part number	10100879
Plating composition	Matte Tin
<u>Bond Wire</u>	
Wire	CuPdAu wire
<u>Die Attach Material</u>	
Epoxy	QMI519 (PFAS free)
<u>Mold Compound</u>	
Mold compound	G700LTD
<u>Package</u>	
Type	8L DFN-S
Package size	6 x 5 x 0.9mm



MICROCHIP **PACKAGE QUALIFICATION REPORT**

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-262601261.000	GRSM423482872.110	2539AA7
MMT-263100036.000	GRSM424391420.120	2544U2M
MMT-263100037.000	GRSM424391420.121	2544U2P

Result

☒ Pass ☐ Fail ☐ _____

8L DFN-S (6x5x0.9mm) assembled by MMT pass reliability test per QCI-39000.
This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C
reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Moisture/Reflow Sensitivity Classification Test (At MSL Level 1)	85°C/ 85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 (IPC/JEDEC J-STD-020E)	IPC/JEDEC J-STD-020E	135(0)	135(0) 0/135	Pass	
<u>Precondition Prior Perform Reliability Tests</u> (At MSL Level 1)	Electrical Test: +25°C, 85°C and 125°C System: NEXTEST_PT Bake 150°C, 24 hrs System: CHINEE 85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 Electrical Test: +25°C, 85°C and 125°C System: NEXTEST_PT	JESD22- A113	693(0) 693(0)	0/693 0/693 0/693 0/693 0/693	Pass Pass	Good Devices

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: -55°C to +150°C, 1000 Cycles System : TABAI ESPEC TSA-70H Electrical Test: +25°C, 85°C and 125°C System: NEXTEST_PT	JESD22-A104		231		Parts had been pre-conditioned at 260°C
			231(0)	0/231	Pass	
	Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>15.00 grams)		45(0)	0/45	Pass	
	Stress Condition: -55°C to +150°C, 2000 Cycles System: TABAI ESPEC TSA-70H Electrical Test: +25°C, 85°C and 125°C C System: NEXTEST_PT		231(0)	0/231	Pass	
	Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>15.00 grams)		45(0)	0/45	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: 5.5 Volts System: HAST 6000X	JESD22-A110		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C, 85°C and 125°C System: NEXTEST_PT		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>15.00 grams)		45(0)	0/45	Pass	
	Stress Condition: +130°C/85%RH, 192 hrs. Bias Volt: 5.5 Volts System: HAST 6000X			231		
	Electrical Test: +25°C, 85°C and 125°C System: NEXTEST_PT		231(0)	0/231	Pass	
	Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>15.00 grams)		45(0)	0/45	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: NEXTEST_PT		231(0)	0/231	Pass	77 units / lot
High Temperature Storage Life	Stress Condition: Bake 175°C, 500 hrs System: TPS Bake Oven	JESD22-A103		135		45 units / lot
	Electrical Test: +25°C, 85°C and 125°C System: NEXTEST_PT		135(0)	0/135	Pass	
	Stress Condition: Bake 175°C, 1000 hrs System: TPS Bake Oven			135		
	Electrical Test: +25°C, 85°C and 125°C System: NEXTEST_PT		135(0)	0/135	Pass	
Solderability Temp 245°C	Steam Aging: Temp 93°C, 8Hrs System: SAS-3000	J-STD-002		22		
	Solder Dipping: Solder Temp. 245°C Solder material: Pb Free Sn 95.5Ag3.9Cu0.6 System: ERS A RA 2200D			22		
	Visual Inspection: External Visual Inspection		22(0)	0/22	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Physical Dimensions	Physical Dimension, 10 units from 1 lot	JESD22- B100/B108	30(0) Units	0/30	Pass	
Bond Strength Data Assembly	Wire Pull (> 3.00 grams)	Mil. Std. 883-2011	30 (0) Wires	0/30	Pass	
	Bond Shear (>15.00 grams)	CDF-AEC- Q100-001	30 (0) Bonds	0/30	Pass	

Eliminating PFAS from Microchip ICs



A Leading Provider of Smart, Connected and Secure Embedded Control Solutions



SMART | CONNECTED | SECURE

Microchip
August 2025

Eliminating PFAS from MCHP ICs

- **What is PFAS**
- **Microchip's Environmental Stewardship**
- **Microchip Products with PFAS**
- **Time Frame to PFAS-Free Die Attach**
- **What is Die Attach**
- **Will clients be required to switch to PFAS free products**
- **Risk Assessment**

What is PFAS: Poly(Per) FluoroAlkyL Substances (**PFAS**)

Poly(Per) FluoroAlkyL Substances (PFAS)

- There may be 12,000 or more PFAS chemicals that are used in small amounts in many different items
 - PFAS can be in the product itself.
 - PFAS can also be used to manufacture products while not in the product itself

PFAS is the new “buzzword” throughout many industries

- Often nicknamed “forever chemicals” because once released into the environment, it never degrades and will accumulate over time
- As PFAS accumulates in the environment over long periods of time, there can be increasing toxicity and polluting effects
- Therefore, government agencies around the globe are considering legislation toward removal of PFAS although PFAS legislations are not fully defined yet

Microchip's Environmental Stewardship

Although very few laws have been enacted regarding PFAS to date, there is a rapidly growing movement among governments around the world to eliminate PFAS

- Initial legislation has targeted on clothing and food products
- Additional legislation and their timings continue to evolving

Companies such as Microchip, which are committed to addressing contaminants in water, air, food, and living organisms, are proactively working to remove PFAS even in the absence of specific legal requirements.

Microchip's suppliers are also taking proactive steps to eliminate PFAS chemicals from the materials they provide to Microchip.

Microchip believes it is prudent to take immediate action toward offering PFAS-free products to all clients, regardless of application, industry, country, or current regulatory requirements.

Achieving “PFAS-Free” status may serve as a competitive advantage for both Microchip and its clients.

Microchip products with PFAS

The primary material in Microchip products containing PFAS is known as die attach. PFAS-free die attach is not new to either Microchip or the industry; in fact, Microchip has shipped hundreds of millions of units utilizing PFAS-free die attach.

Both PFAS and PFAS-free die attach materials are currently in use because PFAS was not previously identified as a substance of concern.

The change announced in this Product Change Notification (PCN) for Microchip-owned factories involves transitioning to the same PFAS-free die attach that has already been qualified and used in other products.

Time Frame to PFAS-Free Die Attach

Qualification of products assembled at Microchip-owned factories has been completed.

While inventory containing PFAS die attach will continue to be shipped, the implementation of PFAS-free die attach in the assembly process is scheduled to begin as early as September 3, 2025.

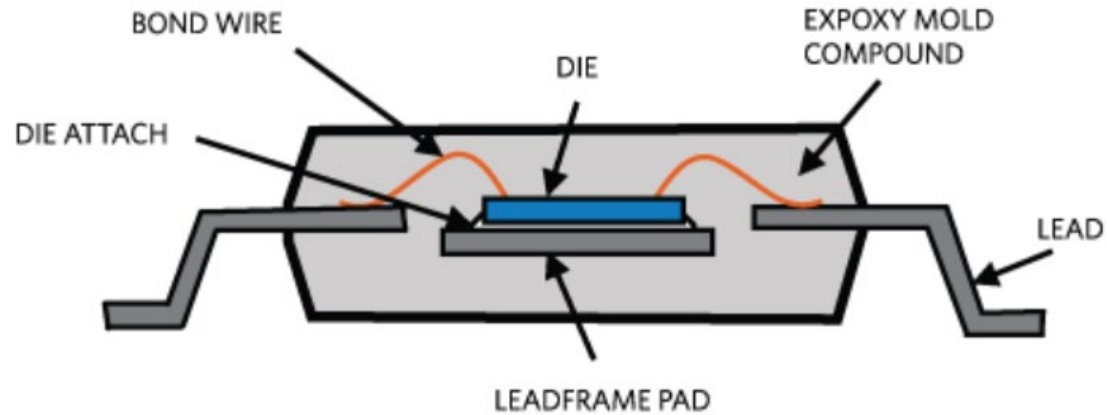
Microchip will consume all existing inventory and die attach, so the exact implementation date will depend on when current inventories are depleted.

- For PPAP clients IMDS/CAMDS material content declarations will be updated.

Schedules for assembly locations not owned by Microchip (subcontractors or "subcons") are currently under review. We anticipate a similar mix of products already utilizing both PFAS and PFAS-free die attach at these locations.

Product Change Notifications (PCNs) announcing die attach changes at subcontractor sites will be issued once schedules are finalized. We expect these timelines to be similar to those for our internal factories.

What is die attach



A thin layer of epoxy between the silicon die and copper pad portion of the lead frame.

- Holds the die in place during the wire bond and mold encapsulation processes
- The bottom of the die has no transistors or active circuits.
- The interface is identical regardless of device type, fab location, technology node, wire material etc.
- **Therefore, allows extremely broad range of products to be grouped into a single qualification.**

Will Clients be required to switch to PFAS-Free Products

The timeline for legislation to eliminate PFAS chemicals remains uncertain; however, regulatory action is anticipated.

Suppliers of PFAS chemicals and raw materials containing PFAS are already announcing end-of-life plans in advance of any formal legislation.

It is expected that suppliers will discontinue offering die attach materials containing PFAS within the next two years, regardless of when government regulations take effect.

While Microchip is committed to providing as much transition time as possible for our clients, we strongly encourage you to begin planning now to avoid potential supply interruptions.

Risk Assessment:



Microchip does not anticipate that this change will impact our clients for the following reasons:

- Microchip has been using PFAS-free die attach material for several years.
- We have shipped hundreds of millions of units utilizing this material without incident.
- Die Attach is not application relevant.

Given these factors, Microchip believes there is minimal cause for concern regarding this change, and additional client qualifications would be redundant and time-consuming. However, if you have any questions that are not addressed in the PCN or this presentation, please do not hesitate to contact us.

